

9014M



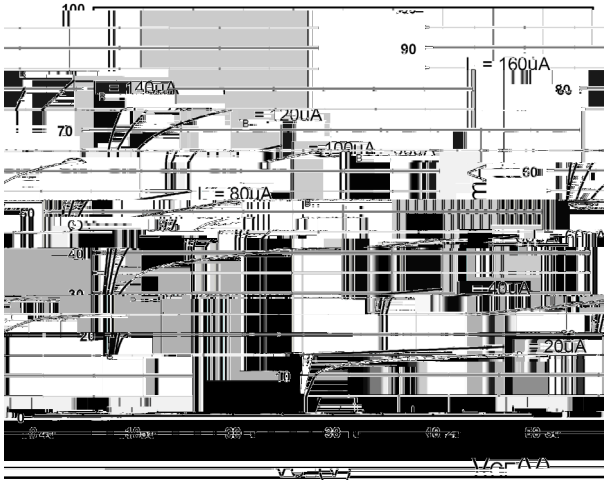
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	45	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current	I_C	100	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=0.1mA$ $I_E=0$	50			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=1.0mA$ $I_B=0$	45			V
Emitter to Base Breakdown	V_{EBO}	$I_E=0.1mA$ $I_C=0.1mA$	5.0			V

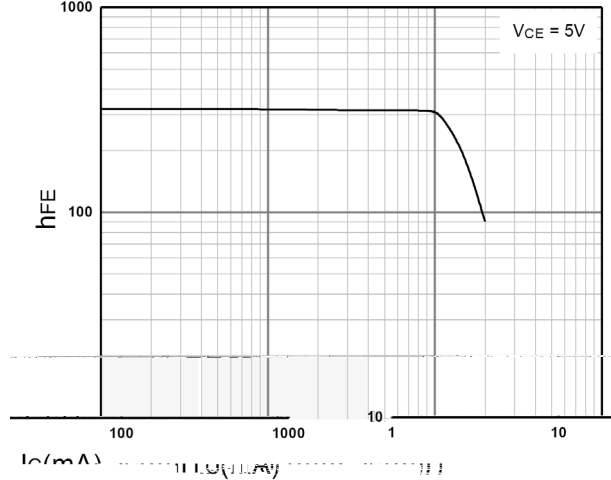
Collector Current I_C 100mA $V_{CE} = V_{CE0}$ $V_{BE} = 0V$ $T_j = 25^\circ C$ $P_C = 200mW$ V_{CE0} 45V V_{BE0} 5.0V T_j 150°C

/ Electrical Characteristic Curve

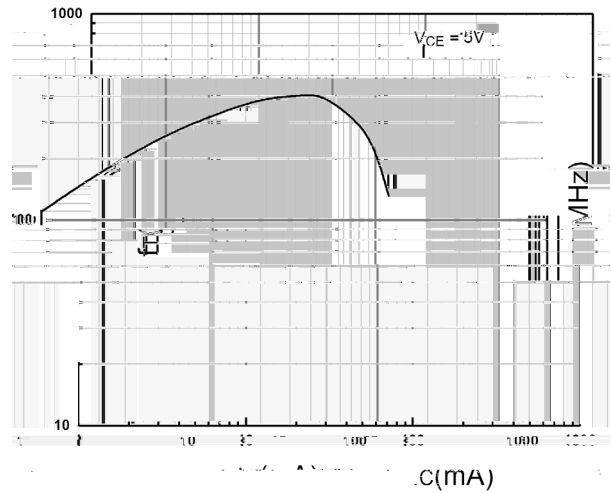
$I_C - V_{CE}$



$h_{FE} - I_C$



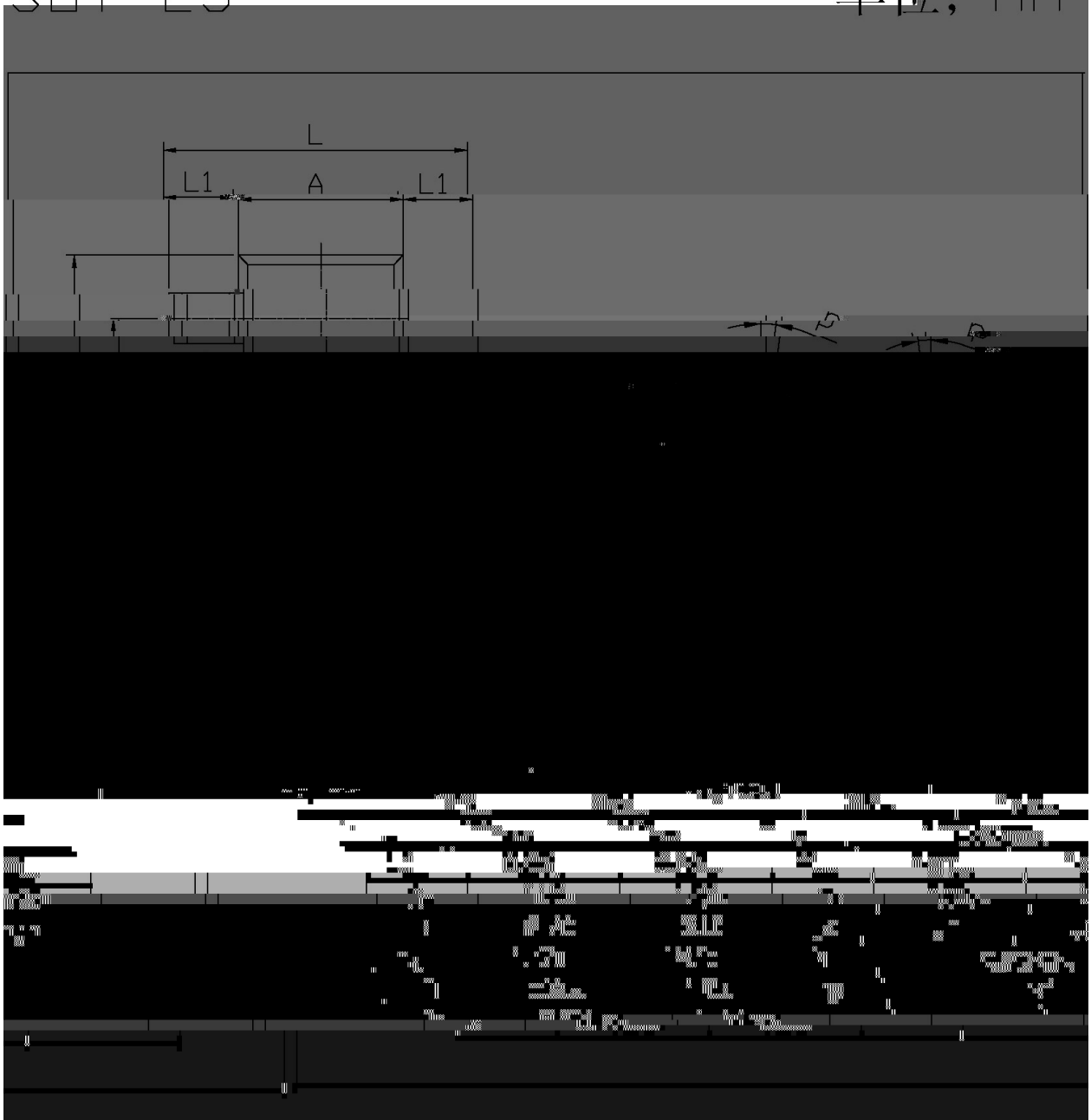
$f_T - I_C$



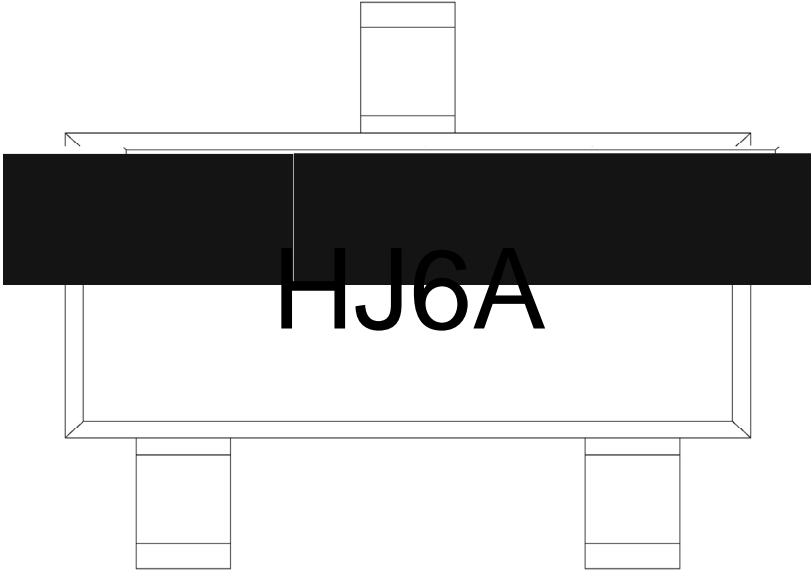
/ Package Dimensions

SOT-23

单位: mm



/ Marking Instructions



- H
 - J6
 - A h_{FE}
- Note:
- H Company Code
 - J6 Product Type Code
 - A h_{FE} Classifications Symbol Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- | | | | | | |
|---|-------|-----|-------|--------|---|
| | | | | Note: | |
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL